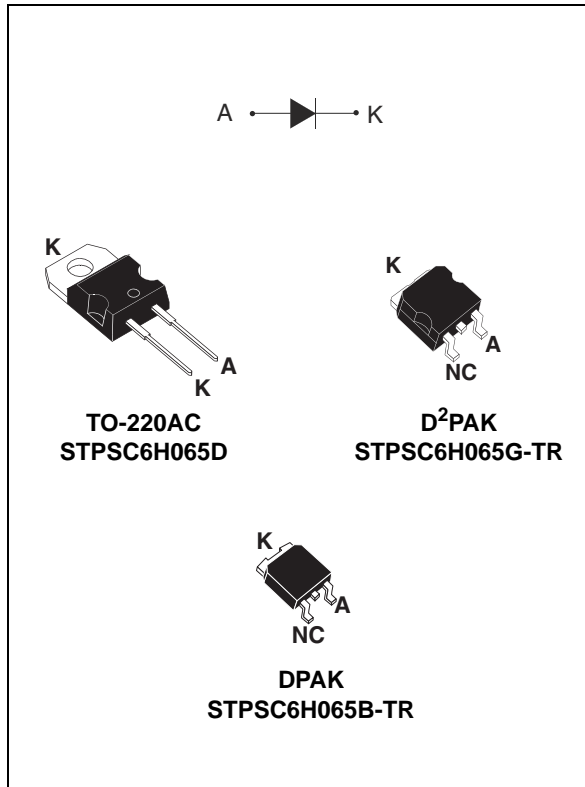


650 V power Schottky silicon carbide diode

Datasheet - production data



Description

The SiC diode is an ultrahigh performance power Schottky diode. It is manufactured using a silicon carbide substrate. The wide band gap material allows the design of a Schottky diode structure with a 650 V rating. Due to the Schottky construction, no recovery is shown at turn-off and ringing patterns are negligible. The minimal capacitive turn-off behavior is independent of temperature.

Especially suited for use in PFC applications, this ST SiC diode will boost the performance in hard switching conditions. Its high forward surge capability ensures a good robustness during transient phases.

Table 1. Device summary

Symbol	Value
$I_{F(AV)}$	6 A
V_{RRM}	650 V
T_j (max)	175 °C

Features

- No or negligible reverse recovery
- Switching behavior independent of temperature
- Dedicated to PFC applications
- High forward surge capability

1 Characteristics

Table 2. Absolute ratings (limiting values at 25 °C unless otherwise specified)

Symbol	Parameter		Value	Unit
V _{RRM}	Repetitive peak reverse voltage		650	V
I _{F(RMS)}	Forward rms current		22	A
I _{F(AV)}	Average forward current	T _C = 135 °C ⁽¹⁾ , DC	6	A
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal, T _C = 25 °C	60	A
		t _p = 10 ms sinusoidal, T _C = 125 °C	52	
		t _p = 10 μs square, T _C = 25 °C	400	
I _{FRM}	Repetitive peak forward current	T _C = 135 °C ⁽¹⁾ , T _j = 175 °C, δ = 0.1	22	A
T _{stg}	Storage temperature range		-55 to +175	°C
T _j	Operating junction temperature ⁽²⁾		-40 to +175	°C

- Value of T_C = 135 °C based on R_{th(j-c)} max.
- $\frac{dP_{tot}}{dT_j} < \frac{1}{R_{th(j-a)}}$ condition to avoid thermal runaway for a diode on its own heatsink

Table 3. Thermal resistance

Symbol	Parameter	Value		Unit
		Typ.	Max.	
R _{th(j-c)}	Junction to case	1.6	2.4	°C/W

Table 4. Static electrical characteristics

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
I _R (1)	Reverse leakage current	T _j = 25 °C	V _R = V _{RRM}	-	5	60	μA
		T _j = 150 °C		-	50	250	
V _F (2)	Forward voltage drop	T _j = 25 °C	I _F = 6 A	-	1.56	1.75	V
		T _j = 150 °C		-	1.98	2.5	

- t_p = 10 ms, δ < 2%
- t_p = 500 μs, δ < 2%

To evaluate the conduction losses use the following equation:

$$P = 1.35 \times I_{F(AV)} + 0.192 \times I_{F(RMS)}^2$$

Table 5. Other parameters

Symbol	Parameter	Test conditions	Typ.	Unit
Q _{cj} ⁽¹⁾	Total capacitive charge	V _R = 400 V	18	nC
C _j	Total capacitance	V _R = 0 V, T _C = 25 °C, F = 1 MHz	300	pF
		V _R = 400 V, T _C = 25 °C, F = 1 MHz	30	

- Most accurate value for the capacitive charge: $Q_{cj} = \int_0^{V_{OUT}} C_j(V_R).dV_R$

Figure 1. Forward voltage drop versus forward current (typical values, low level)

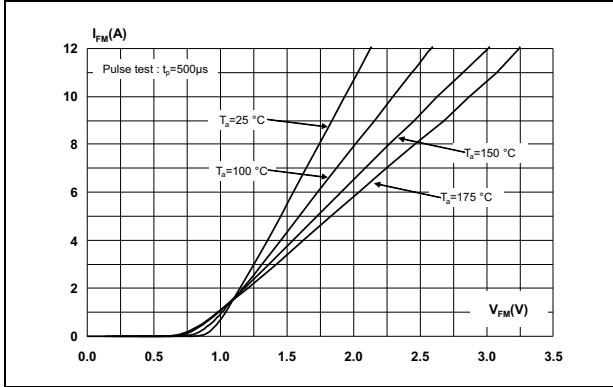


Figure 2. Forward voltage drop versus forward current (typical values, high level)

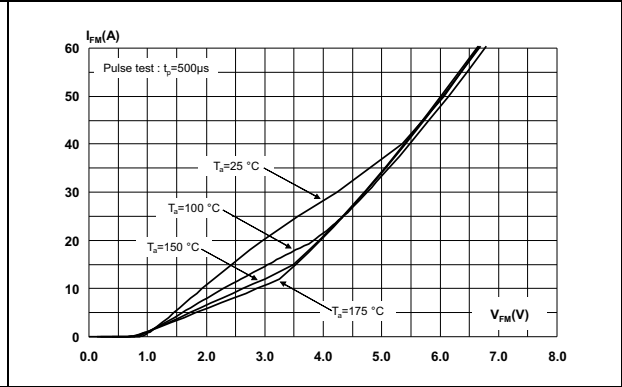


Figure 3. Reverse leakage current versus reverse voltage applied (typical values)

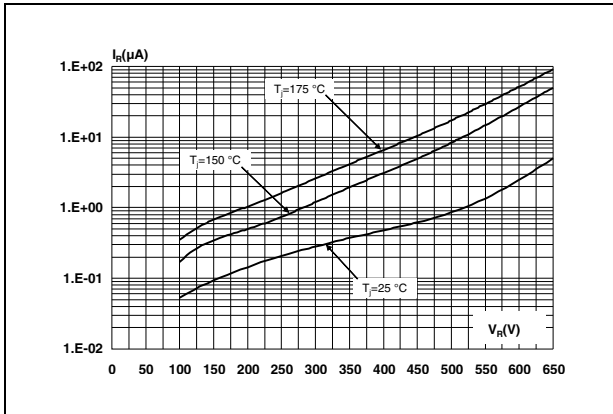


Figure 4. Peak forward current versus case temperature

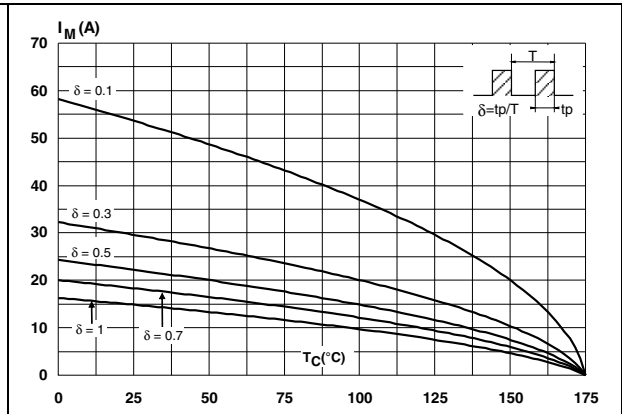


Figure 5. Junction capacitance versus reverse voltage applied (typical values)

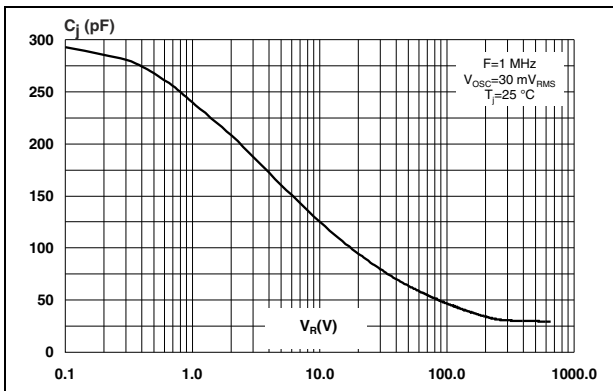


Figure 6. Relative variation of thermal impedance junction to case versus pulse duration

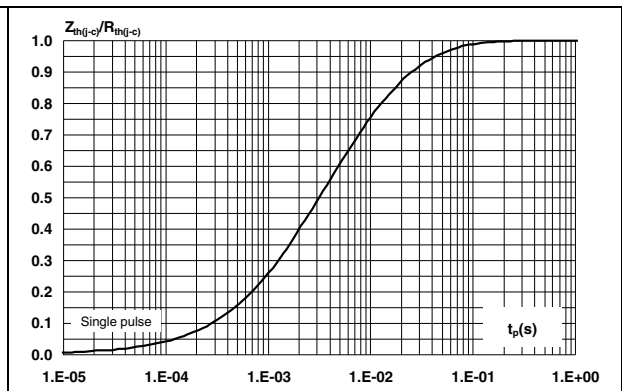


Figure 7. Non-repetitive peak surge forward current versus pulse duration (sinusoidal waveform)

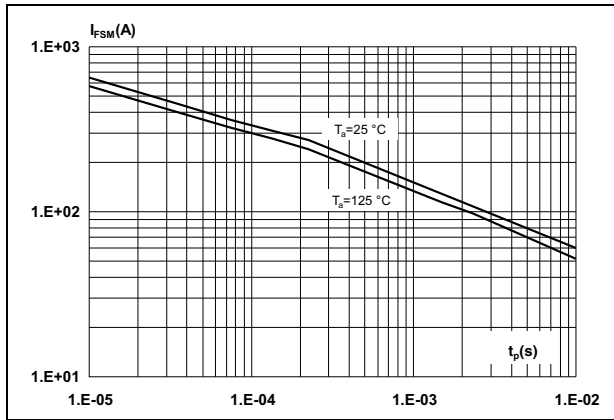
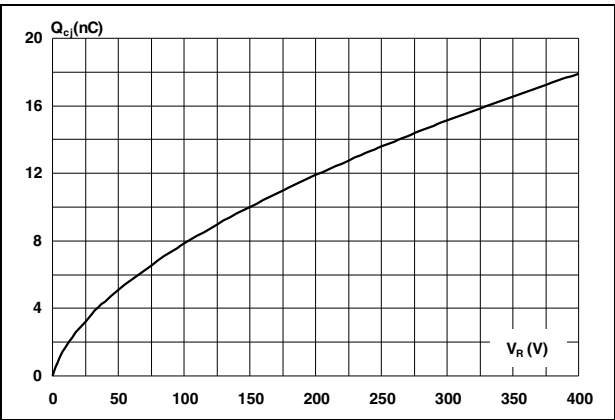


Figure 8. Total capacitive charges versus reverse voltage applied (typical values)



2 Package information

- Epoxy meets UL94, V0
- Recommended torque value (TO-220AC): 0.4 to 0.6 N·m
- Cooling method: conduction (C)

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 9. TO-220AC dimension definitions

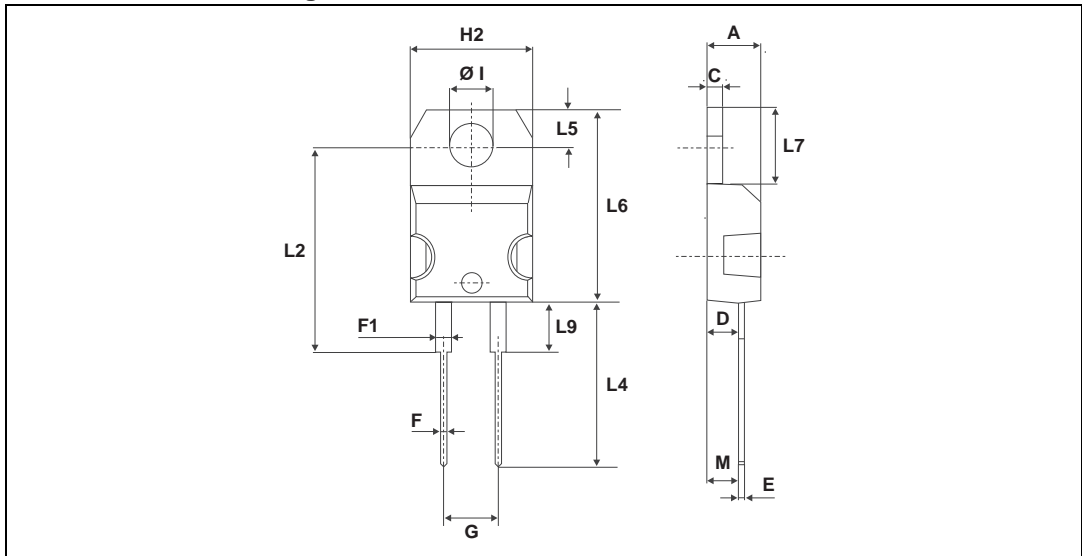


Table 6. TO-220AC dimension values

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

Figure 10. DPAK dimension definitions

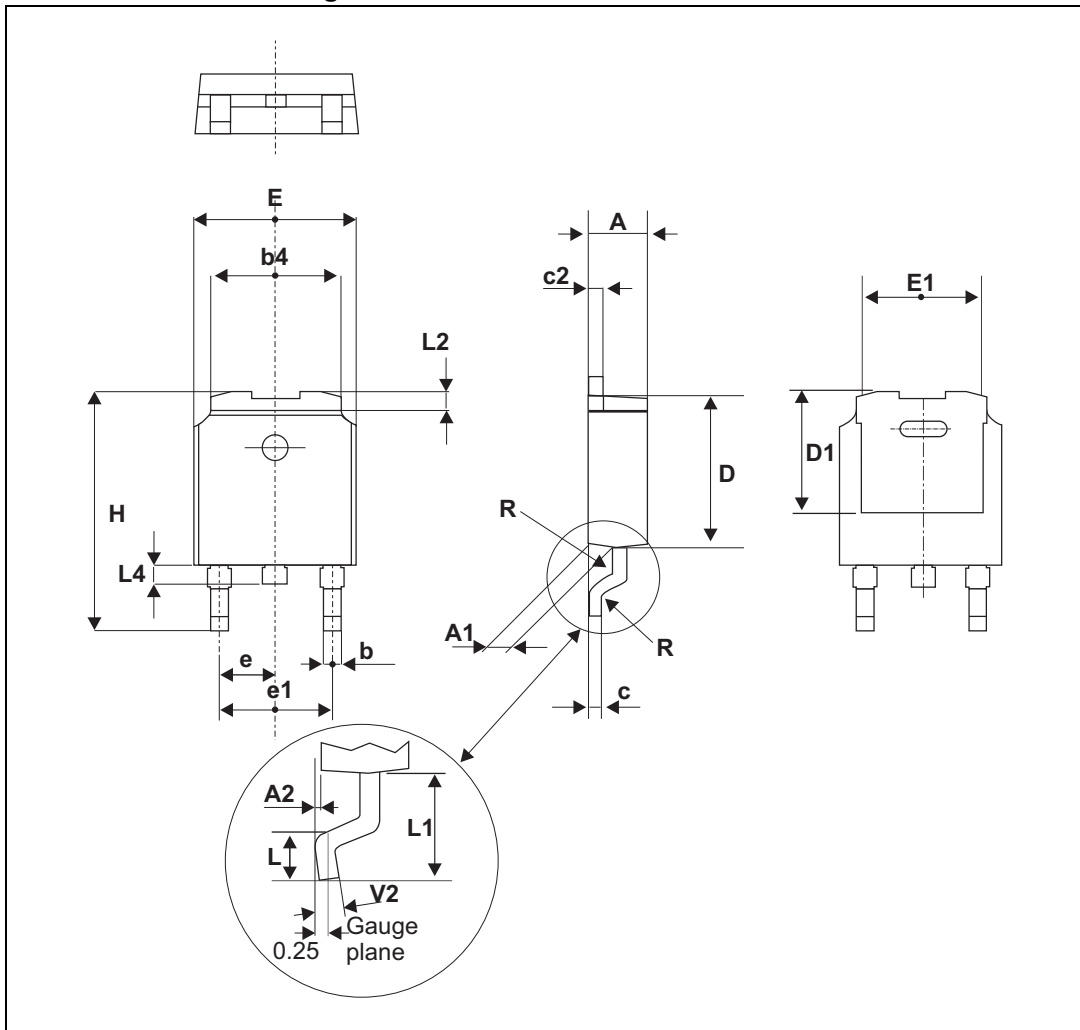


Table 7. DPAK dimension values

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.086		0.094
A1	0.90		1.10	0.035		0.043
A2	0.03		0.23	0.001		0.009
b	0.64		0.90	0.025		0.035
b4	5.20		5.40	0.204		0.212
c	0.45		0.60	0.017		0.023
c2	0.48		0.60	0.018		0.023
D	6.00		6.20	0.236		0.244
D1		5.10			0.201	
E	6.40		6.60	0.251		0.259
E1		4.70			0.185	
e		2.28			0.090	
e1	4.40		4.60	0.173		0.181
H	9.35		10.10	0.368		0.397
L	1.00		1.50	0.039		0.059
L1		2.80			0.11	
L2		0.80			0.032	
L4	0.60		1.00	0.023		0.039
R		0.2			0.008	
V2	0°		8°	0°		8°

Figure 11. Footprint (dimensions in mm)

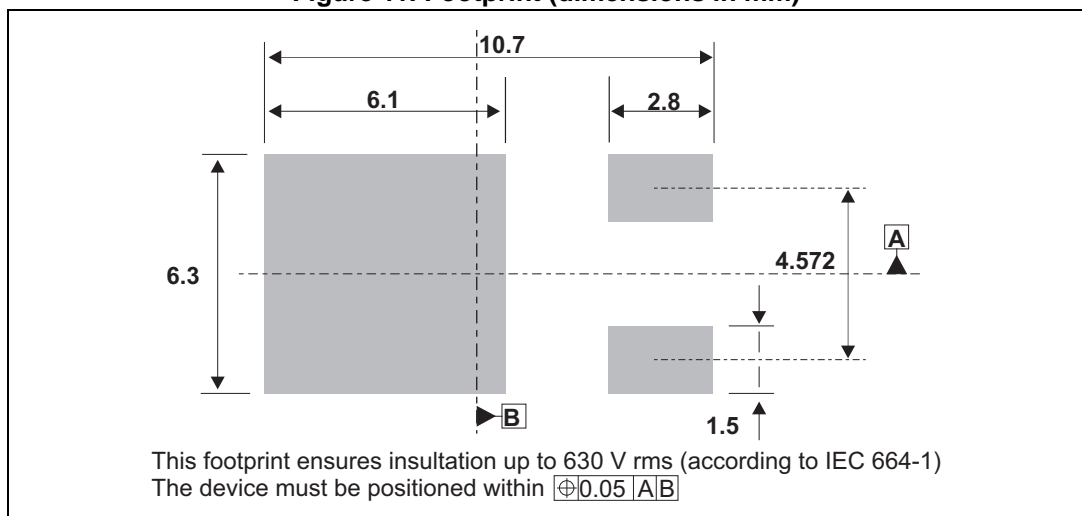


Figure 12. D²PAK dimension definitions

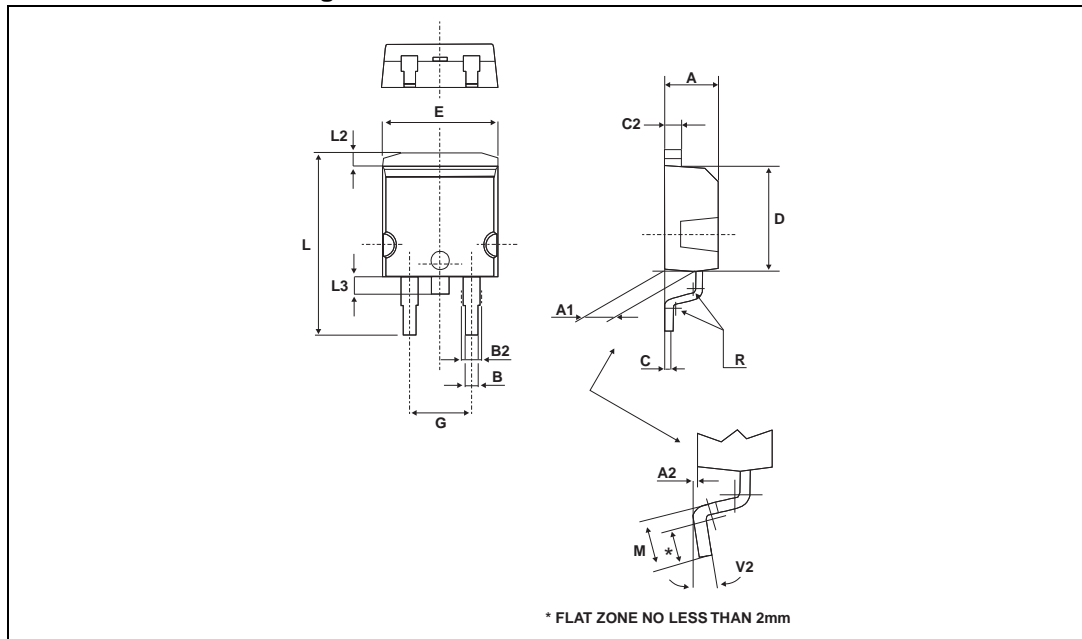
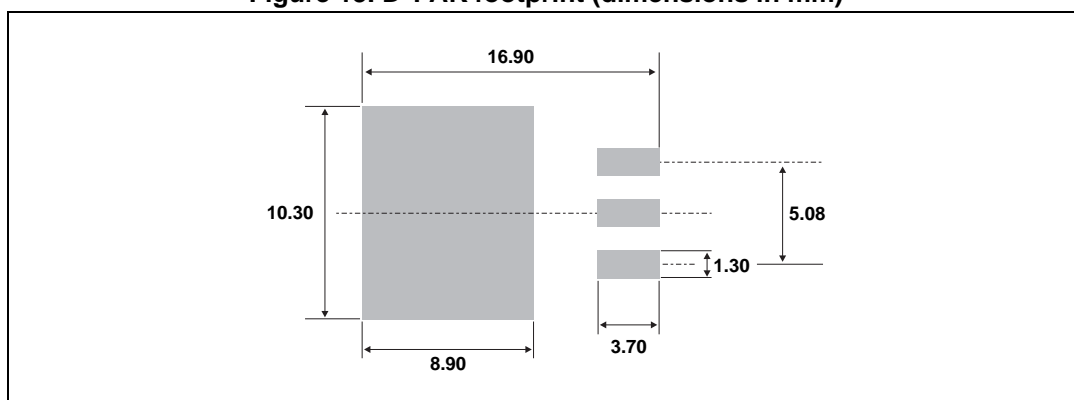


Table 8. D²PAK dimension values

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

Figure 13. D²PAK footprint (dimensions in mm)



3 Ordering information

Table 9. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STPSC6H065D	STPSC6H065D	TO-220AC	1.86 g	50	Tube
STPSC6H065G-TR	STPSC6H065G	D ² PAK	1.48 g	1000	Tape and reel
STPSC6H065B-TR	STPSC 6H065	DPAK	0.32 g	2500	Tape and reel

4 Revision history

Table 10. Document revision history

Date	Revision	Changes
18-Jun-2012	1	First issue.
31-Aug-2012	2	Added diode configuration graphic on front page. Updated value of Q_{cj} and footnote equation in Table 5 .
10-Oct-2012	3	Added Max. value in Table 3 .
07-Nov-2013	4	Updated Figure 1 , Figure 2 , Figure 10 , Figure 11 , and Table 7 .

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